

2009 EDITORIAL CALENDAR

▼ 2D/3D DEVICE ASSEMBLY, PACKAGING
INTERCONNECTS AND MATERIALS

▼ WAFER-LEVEL PACKAGING (WLP)
BACK-END PROCESSING

▼ VENDOR
DIRECTORIES

▼ SHOW AND CONFERENCE
EXTRA DISTRIBUTION

JANUARY-FEBRUARY 2009

Space: Jan. 9 ★ Materials: Jan. 16

- Inspecting overhanging stacked die
- Photovoltaic assembly
- Dispensing, encapsulating and underfilling
- Adhesives

- WLP—Wafer thinning

- Adhesives, encapsulants and underfills

- Pan Pacific Microelectronics Symposium (Hawaii, Feb. 10-12)
- BITS Workshop (Mesa, Ariz., March 8-11)
- IMAPS Device Packaging (Scottsdale, Ariz., March 10-11)
- SEMICON China (Shanghai, March 17-19)

MARCH 2009

Space: Feb. 6 ★ Materials: Feb. 13

- Die attach
- Nanoelectronics assembly
- Solder reflow

- WLP—Photolithography

- Die and flip chip bonders

- APEX and PC Expo (Las Vegas, Nevada, March 31-April 2)

APRIL-MAY 2009

Space: Mar. 6 ★ Materials: Mar. 13

- Annual packaging foundry issue
- IC package design
- Stencil printing
- Optoelectronics assembly

- WLP—Through-Silicon Vias (TSVs)

- Packaging foundries
- Dispensing equipment

- ECTC: Electronic Components & Technology Conference (San Diego, May 26-29)

JUNE 2009

Space: May 1 ★ Materials: May 8

- Semi-annual socket update
- Die attach/bonding
- MEMS • 2D/3D packaging

- WLP—Wafer thinning, stacking and bonding

- Test and burn-in sockets
- WLP lithography tools

JULY 2009

Space: June 5 ★ Materials: June 12

- Photovoltaic assembly
- Wafer bumping services
- LED integration
- Nanotech materials

- WLP—Testing

- Inspection equipment
- Wafer bumping services

- SEMICON West (San Francisco, July 14-16)

AUGUST-SEPTEMBER 2009

Space: July 24 ★ Materials: July 31

- Solder trends
- Thermal management
- Solder ball placement
- 2D/3D device packaging

- WLP—Dicing and singulation

- Singulation and wafer dicing tools

- KGD Conference (Napa, Calif., Sept. 8-9)
- SEMICON Taiwan (Taipei, Sept. 30-Oct. 2)
- SEMICON Europa (Dresden, Oct. 6-8)

OCTOBER 2009

Space: Sept. 4 ★ Materials: Sept. 11

- Package inspection by acoustic, AOI and x-ray units
- Wire bonding
- Acoustic, AOI and x-ray systems

- WLP—Metrology

- Wafer probers and probe cards

- IWLP (6th Annual International Wafer-Level Packaging Conference with 2D/3D Assembly/Packaging) (Marriott, Santa Clara, Calif., Oct. 27-30)
- ITC (Austin, Texas, Nov. 3-5)
- IMAPS (San Jose, Nov. 3-5)

NOVEMBER-DECEMBER 2009

Space: Oct. 2 ★ Materials: Oct. 9

- Semi-annual socket update
- HDI substrates
- Packaging automotive semiconductors
- Flip chip processing

- WLP—UBM and RDL
- Wafer and package cleaning

- Test and burn-in sockets

- SEMICON Korea (Seoul, Jan. 2010)

CHINESE EDITIONS

Space: TBD ★ Materials: TBD

- Editorial to be determined